



**PCN#20141001000
ECAT Label Correction for Selected Devices
Information Only**

Date: 10/1/2014
To: MOUSER PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this PCN are for your information only. Please see the attachment details for the planned implementation date.

This notification period is per TI's standard process. Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20141001000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CSD17551Q3A	null
CSD17552Q3A	null
CSD17577Q3AT	null
CSD25402Q3A	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20141001000			PCN Date:	10/02/2014	
Title:	ECAT Label Correction for Selected Devices					
Customer Contact:	PCN Manager	Phone:	+1(214) 480-6037		Dept:	Quality Services
Change Type:						
<input type="checkbox"/> Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials		
<input type="checkbox"/> Design	<input type="checkbox"/>	Datasheet	<input type="checkbox"/>	Mechanical Specification		
<input type="checkbox"/> Test Site	<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process		
<input type="checkbox"/> Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process		
<input type="checkbox"/> Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process		
	<input type="checkbox"/>	Part number change				

PCN Details

Description of Change:

The ECAT designation on the TI label will be corrected to reflect the actual ECAT designation. There are no material changes to the devices associated with this notification.

		TI Label		
From			(1P) CSD17577Q3A (Q) 2500 (D) 1427 (31T) LOT: 4123626NFM (4W) TKY(1T) 4147551NF2 (P) (2P) REV: A0 (V) 0033317 (20L) CS0:CU3 (21L) CCO:CHN (22L) AS0:NFM (23L) ACO:CHN	
TO			(1P) CSD17577Q3A (Q) 2500 (D) 1427 (31T) LOT: 4082801UAX (4W) TKY(1T) 0004853AE3 (P) (2P) REV: A0 (V) 0033317 (20L) CS0:CU3 (21L) CCO:CHN (22L) AS0:NFM (23L) ACO:CHN	

Reason for Change:
To correct incorrect ECAT information currently on box labels.
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):
None
Changes to product identification resulting from this PCN:
TI Label

Product Affected:			
CSD17551Q3A	CSD17577Q3A	CSD17577Q3AT	CSD25402Q3A
CSD17552Q3A			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com